	REVISIONS		
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
С	Add device types 02 and 03. Editorial changes throughout	94-05-03	M A Frye

The original first page of this drawing has been replaced.

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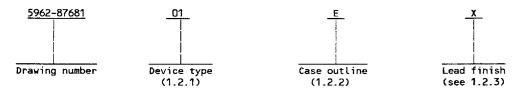
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■ 9004708 0001095 192 **■**

1. SCOPE

1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	1825	High speed PWM controller
02	1825A	High speed PWM controller
03	1825 B	High speed PWM controller

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	<u>Descriptive designator</u>	<u>Terminals</u>	Package style
E	CDIP1-T16 or GDIP2-T16	16	Dual-in-line
2	CQCC1-N2O	20	Square leadless chip carrier
x	CQCC2-N28B	28	Square leadless chip carrier with thermal pads

1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein). Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

Supply voltage (V_{CC}) :	
Device type 01	30 V dc
Device types 02 and 03	22 V dc
DC output current, source or sink	O.5 A
Pulse output current, source or sink $(0.5 \mu\text{s})$	2.0 A
Analog input voltage:	
NONINVERTING, INVERTING, and RAMP pins	-0.3 V dc to 7.0 V dc
SOFT START and CURRENT LIMIT/SD pins	-0.3 V dc to 6.0 V dc
Clock output current	-5.0 mA
Error amplifier output current	5.0 mA
Soft start sink current	20 mA
Oscillator charging current	-5.0 mA
Power dissipation (PD)	1.0 W <u>1</u> / <u>2</u> /
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case (θ_{JC})	See MIL-STD-1835
Junction temperature (T _J)	+150°C

1.4 Recommended operating conditions.

Supply voltage rar	ige:	
Device type O1		10 V dc to 30 V dc
Device types 02	and 03	12 V dc to 22 V dc
Ambient operating	temperature range (T_A)	-55°C to +125°C

1/ For case outline E, derate linearly above $T_A = +60^{\circ}C$ at 11 mW/°C; for case outlines 2 and X, derate linearly above $T_A = 40^{\circ}C$ at 9 mW/°C.

 $\underline{2}/$ Must withstand the added PD due to short circuit test, e.g., $I_{SC}.$

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2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and bulletin. Unless otherwise specified, the following specification, standards and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-I-38535 - Integrated Circuits (Microcircuits) Manufacturing, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-I-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-I-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-I-38535 is required to identify when the QML flow option is used.
- Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) and herein.
 - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
 - 3.2.3 Block diagram(s). The block diagram(s) shall be as specified on figure 2.
- 3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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Test	Symbol Conditions		ıs 1/	 Group A	 Device	 Limi	 Unit	
		-55°C ≤ T _A ≤ + unless otherwise	125°C specified	subgroups	type	Min	Max	
Reference section								
Output voltage	V _{REF}	$T_J = +25^{\circ}C, I_0 = 1.$	O mA	1	ALL	5.05	5.15	v
Line regulation	V _{RLINE}	10 V < V _{CC} < 30 V		1, 2, 3	D1		±20	 mV
	<u> </u> 	12 V < V _{CC} < 20 V			02,03		±15	
Load regulation	V _{RLOAD}	1.0 mA < I _O < 10 mA		1, 2, 3	ALL		±20	m∨
Long term stability <u>2</u> /	ΔV _{REF}	T _J = +125°C, t = 10	100 hrs	2	ALL		±25	m∨
	Δt						<u> </u>	1
Total output variation	V _{OM} 1	I _O = -1.0 mA, V _{CC} =	1, 2, 3	ALL	5.00	5.20	٧	
	V _{OM2}	I _O = -1.0 mA, V _{CC} =	30 V					
	V _{OM3}	I _O = -10 mA, V _{CC} =	10 V					
	V _{OM4}	I _O = -10 mA, V _{CC} =	30 V				 	
Short-circuit current	Isc	V _{REF} = 0 V		1, 2, 3	01	 -15	 -100	mA
Oscillator section	İ			<u>i</u>	02,03	30	90	
Initial accuracy	f _o	T _J = +25°C		4	01	360	440	kHz
					02,03	375	425	
Voltage stability	Δf _o	10 V < V _{CC} < 30 V		4, 5, 6	01		±2.0	1 %
	ΔV	12 V < V _{CC} < 20 V		-	02,03		±1.0	
Total variation	fom1	V _{CC} = 10 V		4, 5, 6	ALL	340	460	kHz
	f _{OM2}	v _{CC} = 30 v		-		 		
See footnotes at end of t	able.			1		1		4
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Test	Symbol		ditions 1/	Group A	Device	Limi	its	_ Unit
		-55°C ≤ TA ≤ + unless otherwise	·125°c	subgroups	type	Min	Max	
Oscillator section - Cont	tinued.							
Clock out high	V _{CLK} (H)			1, 2, 3	01	3.9		_
					02,03	3.7		
Clock out low	VCLK(L)			1, 2, 3	01	<u> </u>	2.9	_
					02,03	ļ	0.2	<u> </u>
Ramp voltage, peak 2/	Vim		_	1, 2, 3	ALL	2.6	3.0	V
Ramp voltage, valley 2/	Viv			1, 2, 3	ALL	0.6	1.25	V
Ramp voltage, valley to peak <u>2</u> /	v _{ivp}			1, 2, 3	ALL	1.6	2.1	V
Error amplifier section					<u> </u>			1
Input offset voltage	v _{os}	V _{CM} = 3.0 V, V _O = 3	.o v	1, 2, 3	ALL	-10	10	mV
Input bias current	IIB	V _{CM} = 3.0 V, V _O = 3	.o v	1, 2, 3	ALL		3.0	μΑ
Input offset current	^I os	V _{CM} = 3.0 V, V _O = 3	.0 v	1, 2, 3	ALL		±1.0	μΑ
Open loop gain	A _{VOL}	1.0 V < V ₀ < 4.0 V		4, 5, 6	ALL	60		dB
Common-mode rejection ratio	CMRR	1.5 V < V _{CM} < 5.5 V V _{OUT} = 3.0 V		4, 5, 6	ALL	75		dB
Power supply rejection ratio	PSRR	10 V < V _{CC} < 30 V V _{OUT} = 3.0 V		4, 5, 6	ALL	85		dB
Output sink current	IO(SINK)	E/A OUT voltage = 1	.0 v	1, 2, 3	All	1.0		mA
Output source current	Io(SOURCE)	E/A OUT voltage = 4	.0 v	1, 2, 3	ALL	-0.5		mA
Output high voltage	V _{ОН1}	E/A OUT current = -	O.5 mA	1, 2, 3	ALL	4.0	5.0	V
See footnotes at end of t	:able.							
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Test	 Symbol	Condition	ıs 1/	 Group A	Device	Limi	ts	 Unit
		-55°C ≤ T _A ≤ + unless otherwise	125°C specified	subgroups	type	Min	Max	
Error amplifier section -	Continued.							
Output low voltage	V _{OL1}	 E/A OUT current = 1	.O mA	1, 2, 3	ALL	0	1.0	V
	BW			4, 5, 6	D1	3.0		MHz
<u>2</u> / Gain bandwidth product	GBWP	F = 200 kHZ		4, 5, 6	02,03	6.0		ļ
Slew rate <u>2</u> /	SR			4, 5, 6	 All 	6.0		V/µs
PWM comparator section								
RAMP bias current	IBRAMP	 RAMP voltage = 0 V		1, 2, 3	 <u>01</u>		-5.0	μА
- <u></u>					02,03	_	-8.0	
Duty cycle range	DC(range)			1, 2, 3	Ail	0	80	1 %
E/A OUT zero do threshold voltage	v _{TH}	RAMP voltage = 0 V	,	1, 2, 3	All	1.1		٧
Delay to output <u>2</u> /	t _D 1			9,10,11	01		100	ns
					02,03		80	<u> </u>
Soft-start/duty cycle cla	mp section							
Charge current	I _{CHG}	SOFT START voltage	= 0.5 V	1, 2, 3	01	3.0	20	μΑ
		SOFT START voltage	= 2.5 V		02,03	8.0	20	
Discharge current	IDCHG	SOFT START voltage	= 1.0 V	1, 2, 3	01	1.0		mA
	<u> </u>		= 2.5 V		02,03	0.10	0.35	
Current limit/shutdown se	ction							
CURRENT LIMIT/SD bias current	IB	O V < CURRENT LIMIT < 4.0 V	/SD voltage	1, 2, 3	01	-15	15	μА
Current limit threshold	V _{LIMIT}			1, 2, 3	01	0.9	1.1	v
Shutdown threshold	 V _{SHTDN}			1, 2, 3	01	1.25	1.55	V
See footnotes at end of t	able.			•				
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		-55°C ≤ T _A ≤ +12 unless otherwise s inued.	5°C pecified	subgroups	type	Min	Max	
Current limit/shutdown section Delay to output $\underline{2}$ /		inued.						
Delay to output 2/ t _{D2}	!							
				9,10,11	01		100	ns
Current limit/start sequence/	fault se	ction						
Restart threshold VRS	1			1, 2, 3	02,03		0.5	V
I LIM bias current I _{BL}	.IM	0 V < V I LIM < 2 V		1, 2, 3	02,03		15	μА
Current limit threshold V _{LI}	MIT			1, 2, 3	02,03	0.95	1.05	V
Over current threshold V _{OV}	'ER	 		1, 2, 3	02,03	1.14	1.26	V
I LIM delay to output t _{D3}				1, 2, 3	02,03		80	nS
Output section					<u> </u>		1	, l- , , - ,
utput low level V _{OL2}	.2	I _{OUT} = 20 mA		1, 2, 3	ALL		0.4	٧
		I _{OUT} = 200 mA		1, 2, 3	ALL		2.2	V
Output high level V _{OH}	2	I _{OUT} = -20 mA		1, 2, 3	ALL	13.0		V
		I _{OUT} = -200 mA		1, 2, 3	ALL	12.0		V
Collector leakage I _{LC}		V _C = 30 V		1, 2, 3	01		500	μΑ
UVLO output low V _{OL}	s	I _O = 20 mA		1, 2, 3	02,03		1.2	V
Rise/Fall time 2/ tr		C _L = 1.0 nF		9,10,11	01		60	ns
					02,03		45	

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Test	Symbol	Conditions 1/ -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		 _ Unit
					Min	 Max 	
Under-voltage lockout	section						
Start threshold	VSTART		1, 2, 3	01	8.8	9.6	_ v
				02	8.4	9.6	
				03		17.0	ļ
Stop threshold	V _{STOP}		1, 2, 3	03	9		V
UVLO hysteresis	V _{HYS}		1, 2, 3	02	0.4	1.2	_ v
				03	5.0	7.0	
Supply current							
Start up current	ISTART	v _{CC} = 8.0 v	1, 2, 3	 01 		2.5	mA
		$V_C = V_{CC} = V_{TH} \text{ (start) } -0.5 \text{ V}$				0.3	
Supply current	I _{CC} INVERTING INPUT, RAMP, and	INVERTING INPUT, RAMP, and	1, 2, 3	01		33	mA
		CURRENT LIMIT/SD voltage = 0 V, NONINVERTING INPUT voltage = 1.0 V		02,03		3 6	
_{CC} = 12 V for device / Guaranteed, if not	types O2 and O3	3. e specified limits.					

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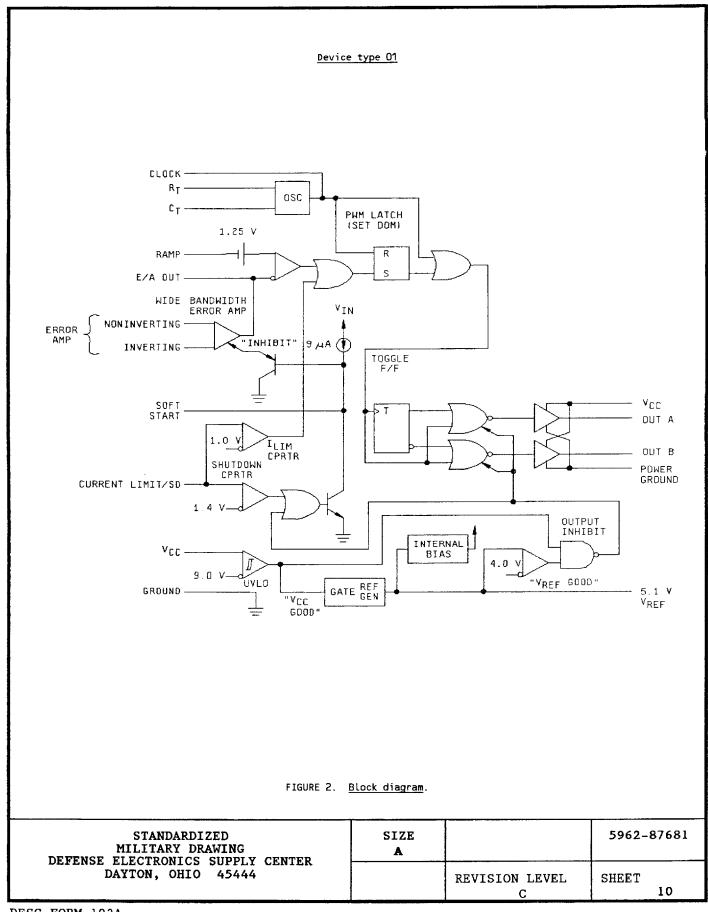
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T T				
Device type	01, 02, 03	01	01, 02, 03	
Case outlines	<u> </u>	2	X	
Terminal number	Terminal symbol			
1 2 3 4 5	INVERTING INPUT NONINVERTING INPUT E/A OUT CLOCK R _T	NC INVERTING INPUT NONINVERTING INPUT E/A OUT CLOCK	NC INVERTING INPUT NONINVERTING INPUT NC NC	
6	c _T	NC	E/A OUT	
7	RAMP	R _T	CLK/LEB	
8	SOFT START	c _T	NC	
9	CURRENT LIMIT/SD	RAMP	R _T	
10	GROUND	SOFT START	c _T	
11 12 13	OUT A POWER GROUND VC	NC CURRENT LIMIT/SD GROUND	NC NC RAMP	
14 15	OUT B	OUT A POWER GROUND	SOFT START NC	
16	V _{REF}	NC	CURRENTLIMIT/SD	
17		v _c	GROUND	
18 19	 	OUT B	NC NC	
20 21 22 22 23		V _{REF}	OUT A POWER GROUND NC VC	
24 25 26 27	 		OUT B NC NC VCC	
28			V _{REF}	

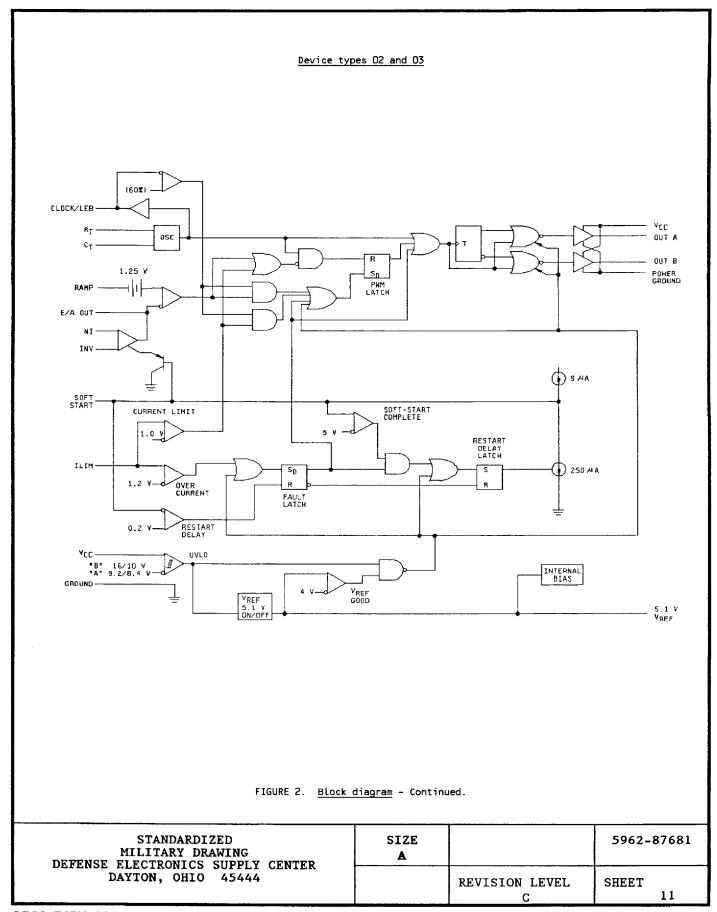
FIGURE 1. <u>Terminal connections</u>.

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- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125$ °C, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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TABLE II. <u>Electrical test requirements</u>.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3, 4,
Group A test requirements (method 5005)	1, 2, 3, 4, 5, 6, 9**, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

- * PDA applies to subgroup 1.
- ** Subgroups 9, 10, and 11 are guaranteed if not tested.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein).

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-Ec.

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